

Specifications



SMD Comm X8G HT150C Flex, Ceramic, 24 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

10
3mm +/-0.4mm
6mm +/-0.3mm
78mm +/-0.20mm
imm MIN
6mm +/-0.25mm
3

W 2.6mm +/-0.3mm  T 0.78mm +/-0.20mm  S 1.5mm MIN  B 0.6mm +/-0.25mm	VA/	26
S 1.5mm MIN	VV	2.6mm +/-0.3mm
S 1.5mm MIN	т	0.79mm ± / 0.20mm
	1	0.7611111 +7-0.2011111
	S	15mm MIN
B 0.6mm +/-0.25mm	0	
- ,	В	0.6mm +/-0.25mm
		,
Packaging Specifications	Packaging Specifications	

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Capacitance	24 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

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